Welcome to today's episode:

Unlock the Power of ToF-SIMS

Technique, Examples and Insights

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COVALENT ACADEMY

Industrial Applications of Advanced Metrology Episode 41



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Electron Microscopy

S/TEM with EDS; EELS; Electron Diffraction; SAED

- FIB-SEM & HR-SEM with EDS; EBSD; 3D Tomography
- Lamella Preparation incl. specialized lift-outs



Failure Analysis

- DPA / Mechanical X-section
- Dye & Pry Test
- EBIC / OBIC failure analysis
- Hot Spot Detection
- NIR / IR Imaging
- Emission Microscopy
- Root-Cause Failure Analysis



Microscopy & Profilometry

Chromatic Aberration

Surfaces

and

Chemicals,

<u>Materials,</u>

- Digital Optical Microscopy
- Laser Scanning Confocal Microscopy
- White Light Interferometry
- Scanning Acoustic Microscopy (SAM)



Mechanical Testing

- AFM & Advanced AFM Modes (EFM, KPFM, MFM, PFM, PiFM)
- Nano-indent / Nano-scratch
- Rheometry / Viscosity
- DMA / TMA (bend/stretch/compression)
- Tensile testing



Analytical Chemistry

- Mass Spectroscopy: ICP-MS and LA-ICP-MS; GCMS
- ICP-OES / GDOES
- Raman
- NMR (solid / liquid + 1,2,3 nuclei)
- XPS, UPS, ISS
- SIMS, TOF-SIMS



Misc. Material Properties

- Thermal Analysis: DSC, TGA
- Surface Zeta Potential
- Porometry / Pycnometry
- Gas Adsorption / Chemisorption
- Foam Density / Skeletal Density / Tap Density
- Particle Analysis: DLS / ELS / size distribution / zeta potential



X-ray Characterization

- X-Ray Diffraction (XRD)
- X-Ray Reflectometry (XRR)
- Micro-computed X-ray Tomography (Micro-CT)
- 2D / 2.5D / 3D X-ray Inspection & X-ray Radiography
- ED-XRF / WD-XRF



Optical Characterization

- Fourier Transformed Infrared Spectroscopy (FTIR and ATR-FTIR)
- Spectral Ellipsometry & Advanced Optical Modeling
- UV-Vis-NIR Spectroscopy

Introducing today's speakers



Dr. Tatyana Kravchuk

Member of Technical Staff, Covalent Metrology

Dr. Kravchuk has recently joined Covalent Metrology as a SIMS specialist. She has over 20 years of experience in Surface Science, with a background in both academia and industry. She also has an extensive track of record in material research and development with a particular focus on batteries and semiconductors. Dr. Kravchuk completed her Bachelor, Master and PhD degrees in Physical Chemistry at the Technion – Isreal Institute of Technology.



Dr. Lyle Gordon

Director of Materials, Chemistry & Surfaces Group, Covalent Metrology

Dr. Gordon joined Covalent in 2023 where he manages the Materials, Chemistry and Surfaces group, overseeing X-ray metrology, analytical chemistry, and surface science. He has extensive expertise in time-of-flight mass spectrometry, particularly related to his work on atom probe tomography. Dr. Gordon completed his Bachelor of Applied Science at the University of Toronto, his PhD in Materials Science at Northwestern University, and was a postdoctoral fellow for the Department of Energy at Pacific Northwest National Lab.



Introduction - brief historical perspective and current use of ToF-SIMS



Technology enhanced their SIMS

systems' depth profiling capabilities, achieving a 20% improvement in depth resolution.



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Introduction - current use of SIMS by industries





Semiconductor IndustryMaterial ScienceGeoscience

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Examples:

- Contamination detection on semiconductor wafers
- Depth profiling in thin films
- Understanding the chemical composition of polymers
- Mapping the distribution of isotopes in a geological samples
- Analyzing drug distribution in tissue.
- Investigating element distributions in battery materials.

Basic principles of ToF-SIMS





- A solid surface is bombarded by primary ions of some keV energy.
- Part of the energy is transported to the surface allowing surface atoms and molecular compounds to overcome the surface binding energy.
- Most of the emitted particles are neutral in charge, but a small portion is also positively or negatively charged.

ToF principles



- TOF mass analysis is based on the fact that ions with the same energy, but different masses will travel with different velocities over a drift path to the detector.
- An electrostatic field accelerates the generated ions to a common energy, then the lighter ions arrive at the detector before the heavier ions.
- Measuring the flight time for each ion allows the determination of its mass.

Static SIMS vs Dynamic SIMS



Static SIMS

- Low ion dose, <10¹² at/cm²
- Ultra surface analysis
- Typically uses gold, bismuth or gallium primary ions
- Elemental and molecular analysis
- Mass analysis is typically performed with TOF spectrometer

Dynamic SIMS



- High ion dose, $> 10^{14}$ at/cm²
- Material removal, depth profiling
- Typically uses oxygen or Cs primary ions
- Elemental analysis
- Usually, quadrupole or magnetic sector mass spectrometers are used

Instrumentation and key components



- A. Time-of-flight mass analyser.
- B. Bismuth cluster ion gun for analysis.
- C. Ion gun, capable of generating Cs⁺ and O_2^+ ions.
- D. Load lock chamber and sample manipulator arm.
- Flood gun for charge compensation
- The 5 axes, X, Y, Z, rotation and tilt macro stage



Dual beam depth profiling advantage





Sputter and analysis conditions can be independently optimized:

- Low energy, high current sputter ion beam provides high depth resolution and fast layers removing
- High energy, low current analysis ion beam provides high lateral resolution and minimal damage to the surface





What can be measured by ToF-SIMS





Spectrum



l m a g e



Depth Profile



3D Render

Surface spectrometry elemental and molecular information from the outer monolayers.	 High sensitivity in the ppm/ppb range High mass resolution (0.005amu) and accuracy even on insulating samples High mass range
Surface imaging mass resolved secondary ion image, "a chemical map", can be obtained simultaneously for all masses.	 Lateral resolution: 0.3 mic Field of view from μm² to cm²
Depth Profiling Distribution of elements in depth can be measured for all masses over measured area	 High sputter speed (up to 10 μm/h) Maximal depth: ~5mic High mass resolution (0.005amu) High sensitivity in the ppm/ppb range Depth resolution: 1nm
3D reconstruction The visualization of 3D sample structures is possible by combining spectral, imaging and depth information.	 Parallel mass detection High depth resolution High image resolution (in image mode) Retrospective analysis 3D reconstruction

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Property	Time of Flight Secondary Ion Mass Spectroscopy (ToF-SIMS)	X-ray Photoelectron Spectroscopy (XPS)	Scanning Electron Microscopy with Energy Dispersive X-ray Spectroscopy (SEM-EDS)	Ion Scuttering Spectroscopy (ISS)		
Surface Sensitivity	Extremely high (monolayer sensitivity)	High (5-10 nm sampling depth)	Low (Bulk material focus)	Extremely high (monolayer sensitivity)		
Elemental Detection Range	All elements and isotopes	All elements except H and He	Elements from B to U	For elements heavier than N		
Chemical State Information	Limited	Yes	Limited	No		
Imaging Capability	Excellent (high spatial resolution)	Poor	Excellent (sub micromrter resolution)	No		
Depth Profiling	Excellent depth resolution up to few microns profiling	Limited depth resolution up to a few microns profiling	No	Excellent depth resolution up to hundreds of nm profiling		
Quantification	Qualitative with relevant reference	Quantitative in most cases	Limited	Qualitative with relevant reference		
Typical Detection Limit	cal Detection Limit ppb 0.10%		0.10%	0.10%		
Destructive Analysis Yes if depth profiling		Yes if depth profiling	No	No		

High

Limited

Low

Example of study of surface contamination over large area, including a high-resolution spectra from 1 amu up to thousands





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3D rendering and data visualization of Ca and Na contamination on Al





GaAs/AlGaAs superlattice depth profile



GaAs/AlGaAs superlattice depth profile

2D overlay of Al, In, Ga of part of the profile

3D rendering of AI from the part of the profile



This TOF-SIMS depth profile of a GaAs/AlGaAs superlattice demonstrates high depth resolution, revealing precise elemental distribution at the nanometer scale. The profile (left) shows clear periodic layering of Al, Ga, and In, while the 2D overlay (center) highlights uniformity and interface sharpness down to 6 nm. The 3D rendering (right) further visualizes Al distribution, emphasizing TOF-SIMS' capability for detailed sub-surface analysis.

Developing ohmic contacts to GaN





Deposition of AZO (Aluminum-doped Zinc Oxide) on GaN followed by 800C annealing created the contact through mutual diffusion of GaN:Mg and AZO



Depth profiles **before** and **after** heating on

Delaminating metal pads investigation







TOF-SIMS reveals the distinct distribution of ¹⁸O, infused through high-temperature and time-controlled process, versus native ¹⁶O in a novel ceramic material, clearly tracking the isotope's 500 µm diffusion path from the surface into the bulk structure.



Investigating paint degradation mechanism using $^{18}\mathrm{O}_2\,$ and TOF-SIMS image of paint cross-section





To investigate paint degradation mechanisms, researchers conducted an experiment using ¹⁸O-labeled **oxygen** as a tracer. Metal samples coated with paint were exposed to **UV light** in an atmosphere containing ¹⁸O₂, simulating environmental aging effects. After exposure, ToF-SIMS was used to measure the ¹⁸O line-scan in paint cross-section which represents penetration depth of ¹⁸O within the paint layer.

The results demonstrated that UV exposure significantly enhanced oxygen diffusion, leading to deeper oxidation within the coating. By distinguishing induced oxidation from naturally occurring oxygen in the samples, this study provided valuable method to investigate **durability and failure mechanisms** for paints, polymers and coatings.

Sample preparation





Data acquisition





We are using Si wafer to check the mass resolution and perform mass calibration every measurement.

Data interpretation





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Strengths and Limitations of ToF-SIMS



Strengths

- Highly surface sensitive
- Exceptional sensitivity to trace elements (parts per million or parts per billion)
- Detects all elements, including hydrogen, and their isotopes simultaneously
- Non-destructive in static mode
- High-resolution depth profiling
- 3D visualization

Limitations

- Quantification requires specific standards
- Matrix effect
- Depth profiling is destructive
- Limited chemical information

⊕ Q

7^K



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Want to learn more about Covalent's ToF-SIMS Services?

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CHARACTERIZATION

OF CLIMATE







SCANNING

TRANSMISSION

INDUCTIVELY

COUPLED PLASMA

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Q & A Session



Thank you.

Positive or negative?





Elemen	t Inforr	nation															×
н															Не		
Li	Ве	e B C N O F													Ne		
Na	Mg	g Al Si P S Cl													CI	Ar	
ĸ	Ca	Sc	Ті	V	Cr	Mn	Fe	Co	Ni	Cu	Zn	Ga	Ge	As	Se	Br	Kr
Rb	Sr	Y	Zr	Nb	Мо	Тс	Ru	Rh	Pd	Ag	Cd	In	Sn	Sb	Те	I.	Xe
Cs	Ba	La	Hf	Та	w	Re	0s	lr.	Pt	Au	Hg	Т	Pb	Bi	Po	At	Rn
Fr	Ra	Ac		Ce	Pr	Nd	Pm	Sm	Eu	Gd	Th	Dv	Ho	Er	Tm	Yh	
								0.11		Ciu Ciu		Oy Ot					
				Ih	Ра	U	Np	Pu	Am	Cm	Bk	Ct	Es	Fm	Md	No	Lr
Eler	nent l	nform	ation						Isoto	opes:							
		16 S)	:	Sulfur				Ma	ss			Abu	ndanc	e		
			Pola	arity i	negati	ive			31.	9720	71		94.9	300 %	6		
	De	ensity	(at./c	m*):	1.98E	22			32.	9714! 9678!	58 67		0.76	00 %			
	Wor	k func	tion (eV]:					35.	9670	B1		4.25	00 %			
	Subli	matio	n ene	ergy 2	2.88												
	lon	izatio	n ene	ergy	10.36												
	E	lectro	on affi	nity 2	2.08	1											
	Elec	tron n	negati	vity 3	2.58												
Esti	mateo	i sput	ter yi	eld (Y	'amar	nura)											
			Prin	nary	Bi	~											
		Ene	rgy (k	eV]:	30					Y	ield fo	or nor	mal 9	9.36			
	Angl	e of iı	ncide	nce:	45.00	1				Yi	ield a	t angl	e of 1	6.38			

Lithium, with its low ionization energy of 5.39 eV and small electron affinity of 0.62 eV, strongly favors positive ion formation.

With a much higher ionization energy of 10.36 eV but a substantial electron affinity of 2.08 eV, Sulfur preferentially forms negative ions.



Which sputter gun to choose?



Oxygen boosts the signal of certain atoms by making them **positively charged**. It does this by forming bonds with metals and then taking electrons when those bonds break.

Cesium bombardment reduces the work function of the sample surface, making it easier for secondary electrons to escape. More available electrons lead to higher **negative ion** yields.

To measure organic layers use **Ar cluster ion beam**.

		Better intensity in positive mode. Use Oxygen for depth profile															
		Both modes can be used															
н		Better intensity in negative mode.												Не			
Li	Be		Us	e Ce	sium	for d	epth	profil	е			В	С	N	0	F	Ne
Na	Mg											AI	Si	Р	S	CI	Ar
к	Са	Sc	Ti	V	Cr	Mn	Fe	Со	Ni	Cu	Zn	Ga	Ge	As	Se	Br	Kr
Rb	Sr	Y	Zr	Nb	Мо	Тс	Ru	Rh	Pd	Ag	Cd	In	Sn	Sb	Те	I	Xe
Cs	Ва	La	Hf	Та	w	Re	Os	Ir	Pt	Au	Hg	ті	Pb	Bi	Ро	At	Rn
Fr	Ra	Ac	Rf	Db	Sg	Bh	Hs	Mt	Ds	Rg	Cn	Nh	FI	Мс	Lv	Ts	Og
				Се	Pr	Nd	Pm	Sm	Eu	Gd	Tb	Dy	Но	Er	Tm	Yb	Lu
				Th	Ра	U	Np	Pu	Am	Cm	Bk	Cf	Es	Fm	Md	No	Lr

Spectra or Image?



Given by laws of physics always a compromise has to be found within the following triangle:



Different positions within the triangle result in different operational modes.

- If you need to identify material -> spectra
- If you know your chemistry and need a good lateral resolution -> image
- If you don't know the chemistry but need a good lateral resolution -> (1) spectra (2) image

Can we have quantitative results?



$$\frac{l_R}{C_R} = RSF_E \cdot \frac{l_E}{C_E}$$



$$C_E = RSF \bullet \frac{I_E}{I_M}$$

 I_{M} = intensity of ion related to matrix and not saturated

- The standard is necessary for proper quantification. It must have the same species in the same matrix as the one we want to quantify.
- The measurement conditions must be the same for standard and for sample.

Good news: Reference standards can typically be manufactured using ion implantation, where a precisely known quantity of the element you're studying is implanted into your material of interest.



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